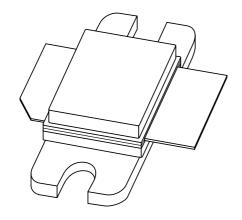
## **DISCRETE SEMICONDUCTORS**

## DATA SHEET



# **BLS2731-110**Microwave power transistor

Product specification Supersedes data of 1998 Jan 30 2001 Dec 05





#### Microwave power transistor

BLS2731-110

#### **FEATURES**

- · Suitable for short and medium pulse applications
- Internal input and output matching networks for an easy circuit design
- Emitter ballasting resistors improve ruggedness
- · Gold metallization ensures excellent reliability
- Interdigitated emitter-base structure provides high emitter efficiency
- Multicell geometry improves power sharing and reduces thermal resistance.

#### **APPLICATIONS**

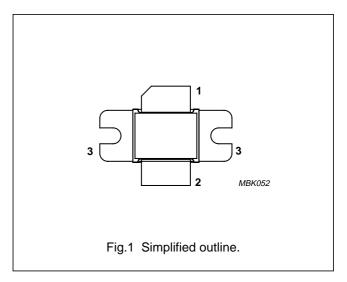
 Common base class-C pulsed power amplifiers for radar applications in the 2.7 to 3.1 GHz band.

#### **DESCRIPTION**

NPN silicon planar epitaxial microwave power transistor in a 2-lead rectangular flange package with a ceramic cap (SOT423A) with the common base connected to the flange.

#### **PINNING - SOT423A**

PIN	DESCRIPTION
1	collector
2	emitter
3	base; connected to flange



#### QUICK REFERENCE DATA

RF performance at  $T_h = 25$  °C in a common base class-C test circuit.

MODE OF OPERATION	f	V <sub>CB</sub>	P <sub>L</sub>	G <sub>p</sub>	ης
	(GHz)	(V)	(W)	(dB)	<b>(%)</b>
Pulsed class-C	2.7 to 3.1	40	>110	>7	>35

#### **WARNING**

Product and environmental safety - toxic materials

This product contains beryllium oxide. The product is entirely safe provided that the BeO disc is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with the general or domestic waste.

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#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	75	V
V <sub>CES</sub>	collector-emitter voltage	R <sub>BE</sub> = 0	_	75	V
$V_{EBO}$	emitter-base voltage	open collector	_	2	V
I <sub>CM</sub>	peak collector current	$t_p \le 100 \ \mu s; \ \delta \le 10\%$	_	12	Α
P <sub>tot</sub>	total power dissipation	$t_p = 100 \ \mu s; \ \delta = 10\%; \ T_{mb} = 25 \ ^{\circ}C$	_	500	W
T <sub>stg</sub>	storage temperature		-65	+200	°C
Tj	operating junction temperature		_	200	°C
T <sub>sld</sub>	soldering temperature	up to 0.2 mm from ceramic cap; t $\leq$ 10 s	_	235	°C

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
Z <sub>th j-h</sub>	thermal impedance from junction to heatsink	$t_p = 100 \ \mu s; \ \delta = 10\%; \ note \ 1$	0.24	K/W

#### Note

#### **CHARACTERISTICS**

 $T_j = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	PARAMETER CONDITIONS		MAX.	UNIT
V <sub>(BR)CBO</sub>	collector-base breakdown voltage	I <sub>C</sub> = 30 mA; open emitter	75	_	V
V <sub>(BR)CES</sub>	collector-emitter breakdown voltage	$I_C = 30 \text{ mA}; V_{BE} = 0$	75	_	V
I <sub>CBO</sub>	collector leakage current	$V_{CB} = 40 \text{ V}; I_{E} = 0$	_	3	mA
I <sub>CES</sub>	collector leakage current	V <sub>CE</sub> = 40 V; V <sub>BE</sub> = 0	_	6	mA
I <sub>EBO</sub>	emitter leakage current	$V_{EB} = 1.5 \text{ V}; I_{C} = 0$	_	0.6	mA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 3 A	40	100	

#### **APPLICATION INFORMATION**

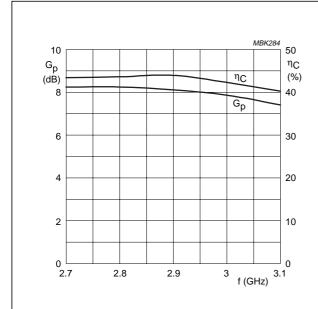
RF performance at  $T_h$  = 25  $^{\circ}C$  in a common base test circuit.

MODE OF OPERATION	f (GHz)	V <sub>CE</sub> (V)	P <sub>L</sub> (W)	G <sub>P</sub> (dB)	η <sub>C</sub> (%)
	2.7 to 3.1	40	≥110	≥7	≥35
Class-C; $t_p = 100 \ \mu s$ ; $\delta = 10\%$	2.7 to 2.9	40	typ. 130	typ. 8	typ. 42
	2.9 to 3.1	40	typ. 120	typ. 7.5	typ. 40

<sup>1.</sup> Equivalent thermal impedance under pulsed microwave operating conditions.

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 $V_{CE}$  = 40 V; class-C;  $t_p$  = 100  $\mu s; \, \delta$  = 10%.

Fig.2 Power gain and efficiency as functions of frequency; typical values.

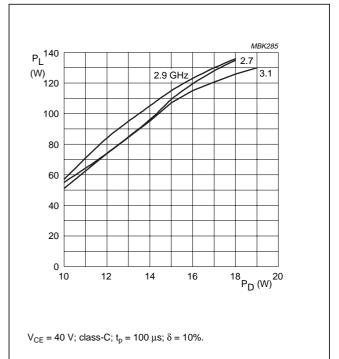


Fig.3 Load power as a function of drive power; typical values.

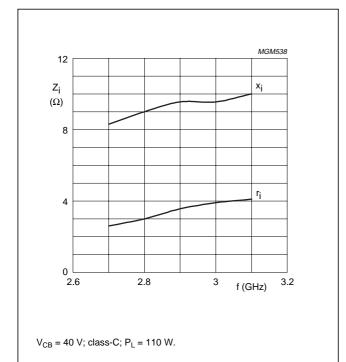
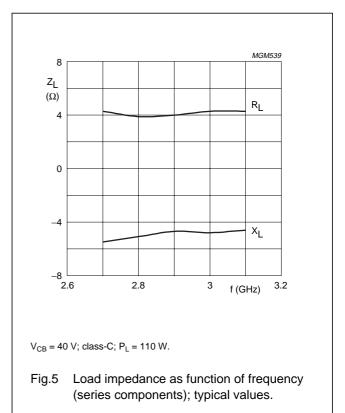


Fig.4 Input impedance as function of frequency (series components); typical values.

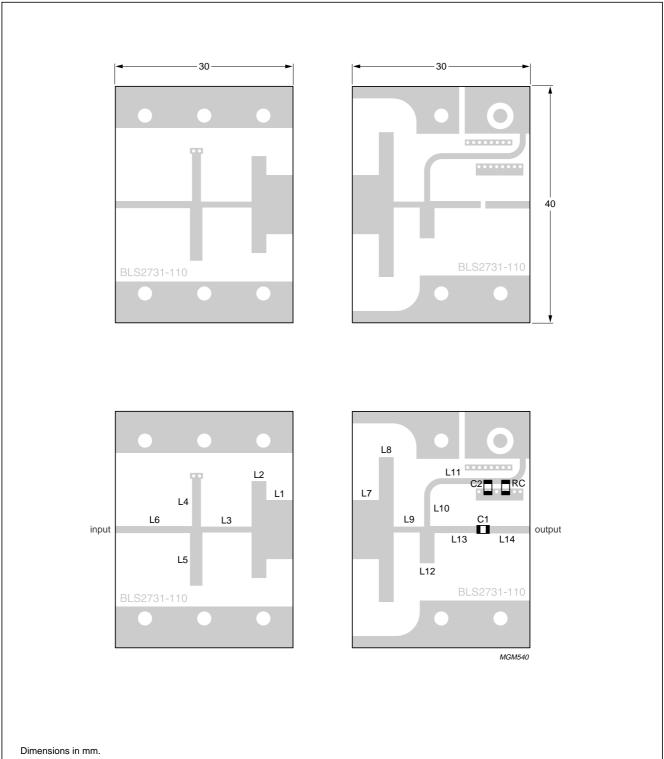


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The components are located on one side of the copper-clad printed-circuit board, the other side is unetched and serves as a ground plane. Earth connections from the component side to the ground plane are made by through metallization.

Fig.6 Component layout for 2.7 to 3.1 GHz class-C test circuit.

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#### List of components (see Fig.6)

COMPONENT	DESCRIPTION	VALUE	DIMENSIONS
C1	multilayer ceramic chip capacitor; note 1	12 pF	
C2	multilayer ceramic chip capacitor; note 1	18 pF	
RC	multilayer ceramic chip capacitor in series with SMD resistor	100 nF + 5 Ω	
L1	stripline; note 2		length 4.5 mm width 10 mm
L2	stripline; note 2		length 2.5 mm width 16.4 mm
L3	stripline; note 2		length 8.3 mm width 1 mm
L4	stripline; note 2		length 8 mm width 1.5 mm
L5	stripline; note 2		length 2 mm width 8.9 mm
L6	stripline; note 2		length 12.7 mm width 1.2 mm
L7	stripline; note 2		length 4.5 mm width 10 mm
L8	stripline; note 2		length 2.5 mm width 24.4 mm
L9	stripline; note 2		length 4.4 mm width 1 mm
L10	stripline; note 2		length 5.2 mm width 1 mm
L11	stripline; note 2		length 9.3 mm width 1 mm
L12	stripline; note 2		length 2.5 mm width 6 mm
L13	stripline; note 2		length 7.8 mm width 1.2 mm
L14	stripline; note 2		length 7.5 mm width 1.2 mm

#### **Notes**

- 1. American Technical Ceramics type 100A or capacitor of same quality.
- 2. The striplines are on double-clad printed-circuit board with Duroid dielectric ( $\epsilon_r = 2.2$ ); thickness = 0.38 mm.

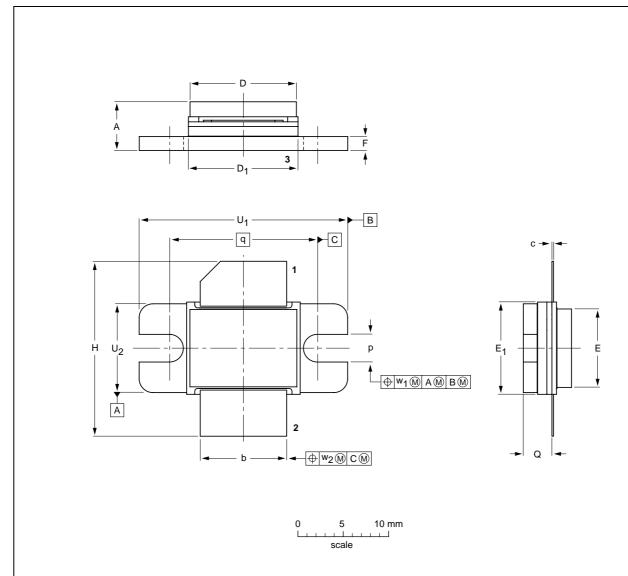
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#### **PACKAGE OUTLINE**

#### Flanged hermetic ceramic package; 2 mounting holes; 2 leads

SOT423A



#### DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	Α	b	С	D	D <sub>1</sub>	E	E <sub>1</sub>	F	н	р	Q	q	U <sub>1</sub>	U <sub>2</sub>	w <sub>1</sub>	w <sub>2</sub>
mm	5.72 4.90	9.53 9.27	0.10 0.05	12.09 11.71	12.83 12.57	8.84 8.56	10.29 10.03	1.58 1.47	19.81 18.29	3.43 3.18	3.35 2.95	16.51	22.99 22.73	9.91 9.65	0.25	0.76
inches	0.225 0.193	0.375 0.365	0.004 0.002	0.476 0.461	0.505 0.495	0.348 0.337	0.405 0.395	0.062 0.058	0.78 0.72	0.135 0.125	0.132 0.116	0.65	0.905 0.895	0.390 0.380	0.01	0.03

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT423A						99-03-29

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#### **DATA SHEET STATUS**

DATA SHEET STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
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Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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NOTES

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NOTES

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